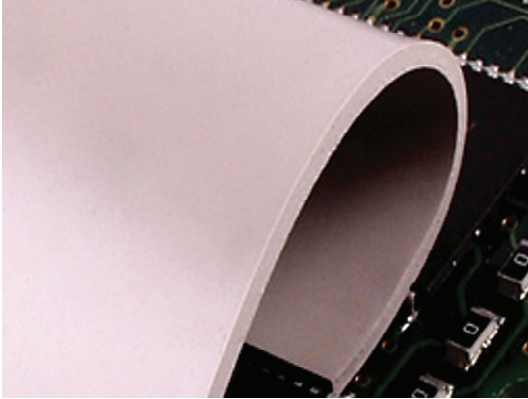


X889

Thermal Composite Material



Features

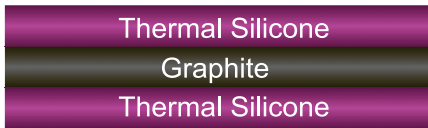
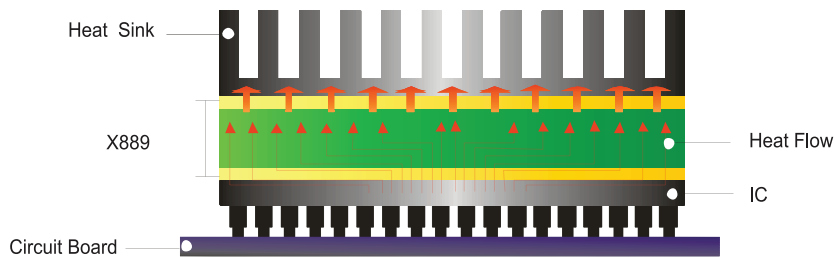
- Good heat spreader
- Good thermal conductivity
- Easy to assemble
- High Stability

Applications

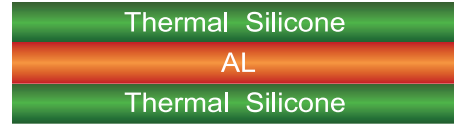
- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

- REACH Compliant
- RoHS Compliant



Composition X889



Composition X889-1

Property	X889	X889-1	Unit	Test Method
Colour	Grey	Grey	-	Visual
Thickness (Available thickness range)	0.25~0.6	0.13	mm	ASTM D374
	0.098~0.0236	0.051	inch	ASTM D374
Thermal Conductivity	X, Y, 400	Z, 4	W/m.k	ASTME 1530
	Z, 5			
Flame Rating	V-0	V-0	-	UL 94
Dielectric Breakdown Voltage	>1	>2	kV	ASTM D149
Weight Loss	<1	<1	%	ASTM E595
Specific Gravity	1.85	1.85	g/cm ³	ASTM D792
Working Temperature	-40 ~ +200	-40 ~ +200	°C	-
Volume Resis	2.2 x 10 ¹²	2.2 x 10 ¹²	Ohm-cm	ASTM D257

Available with an adhesive backing

